

Applicant: Hee-Jin Park, Tae-Jin Park and Eun-Chul Ahn
Serial No. not yet assigned Examiner: not yet assigned
Filing Date: November 20, 2003 Art Unit: not yet assigned
Title: STACKED CHIP PACKAGE WITH HEAT TRANSFER WIRES

**INFORMATION DISCLOSURE CITATION
FORM PTO-1449 (Modified)**

U.S. PATENT DOCUMENTS

<u>Exam Init</u>	<u>Ref</u>	<u>Document Number</u>	<u>Issue Date</u>	<u>Name</u>	<u>Class</u>	<u>Sub Class</u>
—	—	US 6,294,838 B1	9/25/2001	Peng		

FOREIGN PATENT DOCUMENTS

<u>Exam Init</u>	<u>Ref</u>	<u>Document Number</u>	<u>Publication Date</u>	<u>Country</u>	<u>Name</u>
—	—	2002-43395	6/10/2002	Korea	Eun-Yeong Jung
—	—	2002-36191	5/16/2002	Korea	Beak, et al.

OTHER DOCUMENTS

<u>Exam Init</u>	<u>Ref</u>	<u>Author, Title, Date, Pertinent Pages, Etc.)</u>
—	—	English language of Korean Abstract for Korean Patent Publication No. 2002-43395 published 6/10/2002.
—	—	English language of Korean Abstract for Korean Patent Publication No. 2002-36191, published 5/16/2002.

Examiner: _____

Date Considered: _____